

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

**LISTING OF CLAIMS:**

1. and 2. (Cancelled).
3. (Currently amended) A photosensitive resin composition according to claim 11, wherein said at least one diamine used in producing said polyimide precursor consists of a diaminopolysiloxane.
4. (Previously presented) A photosensitive resin composition according to claim 11, wherein said transmittance is in a range of 40%-68%.
5. - 9. (Cancelled).
10. (Currently amended) A photosensitive resin composition which ~~comprises~~consists essentially of (1) a polyimide precursor produced using ~~(a) an oxydiphthalic acid or acid anhydride thereof and at least one diamine as reactants as a reactant~~ for forming the polyimide precursor, wherein said at least one diamine consists of ~~and (b)~~ at least one diamine selected from the group consisting of diaminodiphenyl ether, diaminodiphenyl sulfone, metaphenylene diamine, p-phenylenediamine, p-xylylenediamine, diaminonaphthalene, dimethylbenzidine, dimethoxybenzidine, diaminodiphenylmethane, diaminodiphenylsulfide, benzophenonediamine, bis{(aminophenoxy) phenyl}sulfone, hexafluoro-bis(aminophenyl)propane, bis{(aminophenoxy)phenyl}propane, dimethyl-

diaminodiphenylmethane, bis{(aminophenoxy)phenyl} sulfone, bis(aminophenyl)propane and diaminopolysiloxane, (2) an addition-polymerizable compound, and (3) a photoinitiator, and which is adapted to be exposed and developed using an i-line stepper which uses monochromatic light, the polyimide precursor being such that a 20 µm thick film thereof has a transmittance, at 365nm, of at least 40%.

11. (Original) A photosensitive resin composition according to claim 10, wherein the addition-polymerizable compound is tetraethylene glycol dimethacrylate.

12. (Currently amended) A photosensitive resin composition according to claim 11, wherein said at least one diamine used in producing said polyimide precursor consists ofis a diaminodiphenyl ether.

13. (Currently amended) A photosensitive resin composition according to claim 10, wherein said at least one diamine used in producing said polyimide precursor consists ofis a diaminodiphenyl ether.

14. - 16. (Cancelled).

17. (Currently amended) A photosensitive resin according to claim 13, wherein said at least one~~the~~ diamine used in producing said polyimide precursor consists of at least one diamine~~is~~ selected from the group consisting of 4,4'-diaminodiphenyl ether, 2,4'-diaminodiphenyl ether, 3,4'-diaminodiphenyl ether and 3,3'-diamino-diphenyl ether.

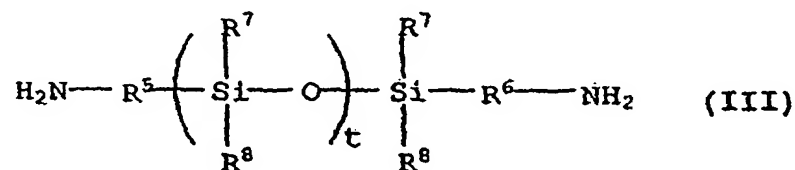
18. (Cancelled).

19. (Currently amended) A photosensitive resin composition according to claim 10, wherein said at least one diamine used in producing said polyimide precursor consists of at least one diamine is selected from the group consisting of 4, 4'-diaminodiphenyl ether, 2, 4'-diaminodiphenyl ether, 3, 4'-diaminodiphenyl ether, 3, 3'-diaminodiphenyl ether, 4, 4'-diaminodiphenyl sulfone, 3, 3'-diaminodiphenyl sulfone and metaphenylenediamine.

20. (Currently amended) A photosensitive resin composition according to claim 19, wherein said at least one diamine used in producing said polyimide precursor consists of at least one diamine is selected from the group consisting of 3, 4'-diaminodiphenyl ether, 3, 3'-diaminodiphenyl sulfone, 4, 4'-diaminodiphenyl sulfone and metaphenylenediamine metaphenylenediamine.

21. (Currently amended) A photosensitive resin composition according to claim 10, wherein the at least one diamine used in producing said polyimide precursor, consisting of said at least one diamine selected from said group, includes a diaminopolysiloxane represented by the formula (III):

(III):



wherein R<sup>5</sup> and R<sup>6</sup> each represent a divalent hydrocarbon group; R<sup>7</sup> and R<sup>8</sup> each represent a monovalent hydrocarbon group; each of R<sup>5</sup>, R<sup>6</sup>, R<sup>7</sup> and R<sup>8</sup> may be the same or different; and t represents an integer of 1 to 5.

22. (Previously presented) A photosensitive resin composition according to claim 21, wherein said divalent hydrocarbon group has 1 to 3 carbon atoms, and said monovalent hydrocarbon group has 1 to 3 carbon atoms.

23. (Previously presented) A photosensitive resin composition which comprises (1) a polyimide precursor produced using (a) an oxydiphthalic acid or acid anhydride thereof as a reactant for forming the polyimide precursor, and (b) at least one diamine including a hydroxyl group-containing diamine, (2) an addition-polymerizable compound, and (3) a photoinitiator, and which is adapted to be exposed and developed using an i-line stepper which uses monochromatic light, the polyimide precursor being such that a 20 µm thick film thereof has a transmittance, at 365 nm, of at least 40%.

24. (Previously presented) A photosensitive resin composition according to claim 10, wherein said polyimide precursor is a condensation product of said oxydiphthalic acid or acid anhydride thereof and said at least one diamine.

25. (Currently amended) A photosensitive resin composition which consists essentially of (1) a polyimide precursor produced using (a) an oxydiphthalic acid or acid anhydride thereof as a reactant for forming the polyimide precursor, and according to claim 10, wherein said (b) at least one diamine is selected from the

group consisting of diaminodiphenyl sulfone, metaphenylene diamine, p-phenylenediamine, p-xylylenediamine, diaminonaphthalene, dimethylbenzidine, dimethoxybenzidine, diaminodiphenylmethane, diaminodiphenylsulfide, benzophenonediamine, bis{(aminophenoxy) phenyl}sulfone, hexafluoro-bis(aminophenyl)propane, bis{(aminophenoxy)phenyl}propane, dimethyl-diaminophenyl-methane, tetramethyl-diaminodiphenylmethane, bis{(aminophenoxy)phenyl} sulfone, bis(aminophenyl)propane and diaminopolysiloxane, (2) an addition-polymerizable compound, and (3) a photoinitiator, and which is adapted to be exposed and developed using an i-line stepper which uses monochromatic light, the polyimide precursor being such that a 20  $\mu$ m thick film thereof has a transmittance, at 365nm, of at least 40%.

26. (New) A photosensitive resin composition according to claim 10, which consists essentially of said polyimide precursor, said addition-polymerizable compound, and said photoinitiator, in an organic solvent.

27. (New) A photosensitive resin composition according to claim 19, which consists essentially of said polyimide precursor, said addition-polymerizable compound, and said photoinitiator, in an organic solvent.

28. (New) A photosensitive resin composition according to claim 23, wherein said polyimide precursor, said addition-polymerizable compound and said photoinitiator are in a solvent.

29. (New) A photosensitive resin composition according to claim 25, wherein said polyimide precursor, said addition-polymerizable compound and said photoinitiator are in a solvent.

30. (New) A photosensitive resin composition according to claim 10, wherein said polyimide precursor is produced by using said oxydiphthalic acid or acid anhydride thereof and said at least one diamine as reactants, in an organic solvent.

31. (New) A photosensitive resin composition according to claim 30, wherein said organic solvent is selected from the group consisting of N-methyl-2-pyrrolidone, N,N-dimethylacetamide, N,N-dimethylformamide, dimethylsulfoxide, tetramethylurea, hexamethylphosphoric triamide and  $\gamma$ -butyrolactone.

32. (New) A photosensitive resin composition according to claim 10, wherein said polyimide precursor has a number average molecular weight of 3,000 to 200,000.

33. (New) A photosensitive resin composition according to claim 32, wherein said number average molecular weight of said polyimide precursor is 7,000 to 50,000.

34. (New) A photosensitive resin composition according to claim 10, wherein said polyimide precursor, said addition-polymerizable compound and said photoinitiator are provided in an organic solvent.

35. (New) A photosensitive resin composition according to claim 10, wherein composition is a solution of said polyimide precursor, said addition-polymerizable compound and said photoinitiator in said organic solvent.

36. (New) A photosensitive resin composition according to claim 19, wherein said polyimide precursor, said addition-polymerizable compound and said photoinitiator are provided in an organic solvent.

37. (New) A photosensitive resin composition according to claim 36, wherein composition is a solution of said polyimide precursor, said addition-polymerizable compound and said photoinitiator in said organic solvent.